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**PATENT ABSTRACTS OF JAPAN**(21) Application number: **06133496**(51) Intl. Cl.: **H01L 21/68 G01B 11/26 H01L 27/14**(22) Application date: **16.06.94**

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(84) Designated contracting states:

(71) Applicant: **NEC YAMAGATA LTD**(72) Inventor: **SATO KATSUAKI**

(74) Representative:

**(54) WAFER POSITIONING APPARATUS**

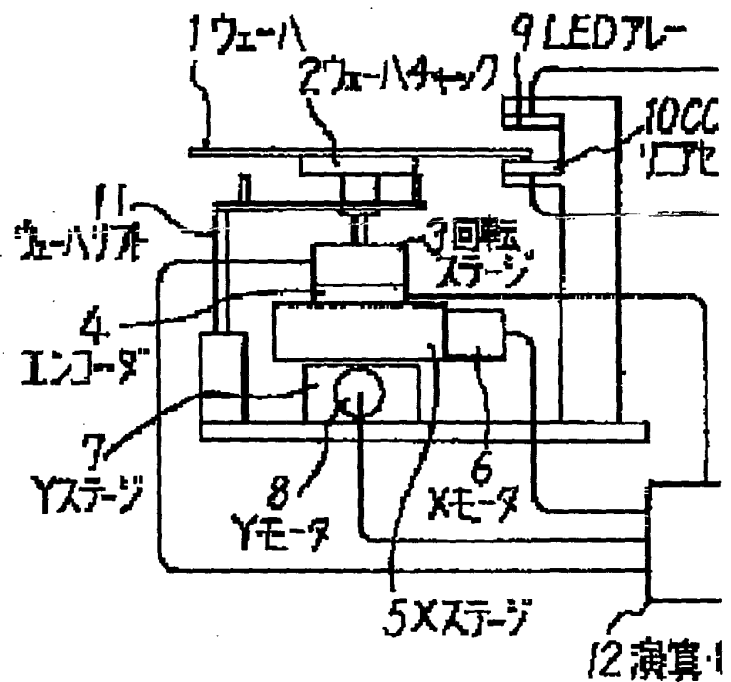
(57) Abstract:

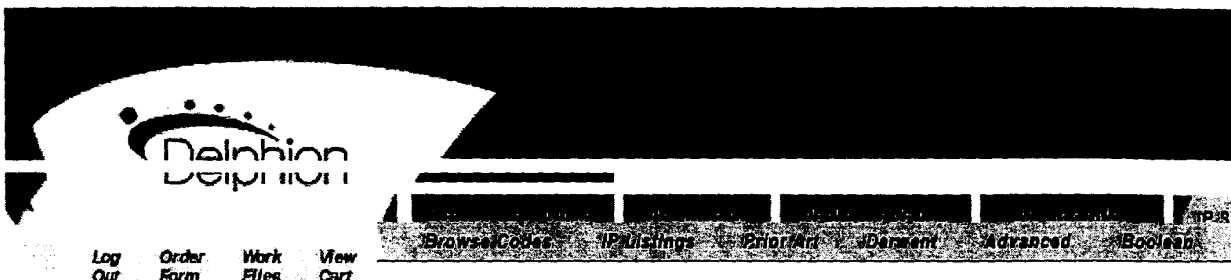
**PURPOSE:** To realize highly accurate centering of a wafer by measuring the positional shift between the centers of the wafer and a rotary stage and the position of orientation flat based on the signals from an angle sensor and a CCD linear sensor.

**CONSTITUTION:** A wafer 1 is sucked to a wafer chuck 2 fixed to a rotary stage 3 also fixed with an angle detector 4. A light projecting section comprises an LED array 9 and a CCD linear sensor 10 is disposed on the wafer surface closely to the under side thereof. An operation control section 12 measures the positional shift between the centers of the wafer and the rotary stage, as well as the position of orientation flat, using the single CCD linear sensor 10 so that the positional shift can be corrected and the orientation flat can be

positioned. This structure can decrease the number of components and since no error is produced theoretically, highly accurate centering of wafer can be realized.

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Title: **JP8008328A2: WAFER POSITIONING APPARATUS**

Country: **JP Japan**

Kind: **A (See also: JP8008328B4 )**

Inventor(s): **SATO KATSUAKI**

Applicant/Assignee:



**NEC YAMAGATA LTD**

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Priority Number(s): **June 16, 1994 JP1994000133496**

Abstract:



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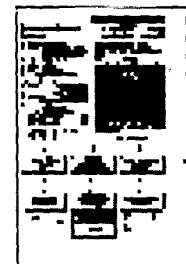
**Constitution:** A wafer 1 is sucked to a wafer chuck 2 fixed to a rotary stage 3 also fixed with an angle detector 4. A light projecting section comprises an LED array 9 and a CCD linear sensor 10 is disposed on the wafer surface closely to the under side thereof. An operation control section 12 measures the positional shift between the centers of the wafer and the rotary stage, as well as the position of orientation flat, using the single CCD linear sensor 10 so that the positional shift can be corrected and the orientation flat can be positioned. This structure can decrease the number of components and since no error is produced theoretically, highly accurate centering of wafer can be realized.

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Family: Show known family members

Other Abstract Info: **DERABS G96-102640 DERG96-102640**

Foreign References: **No patents reference this one**



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